

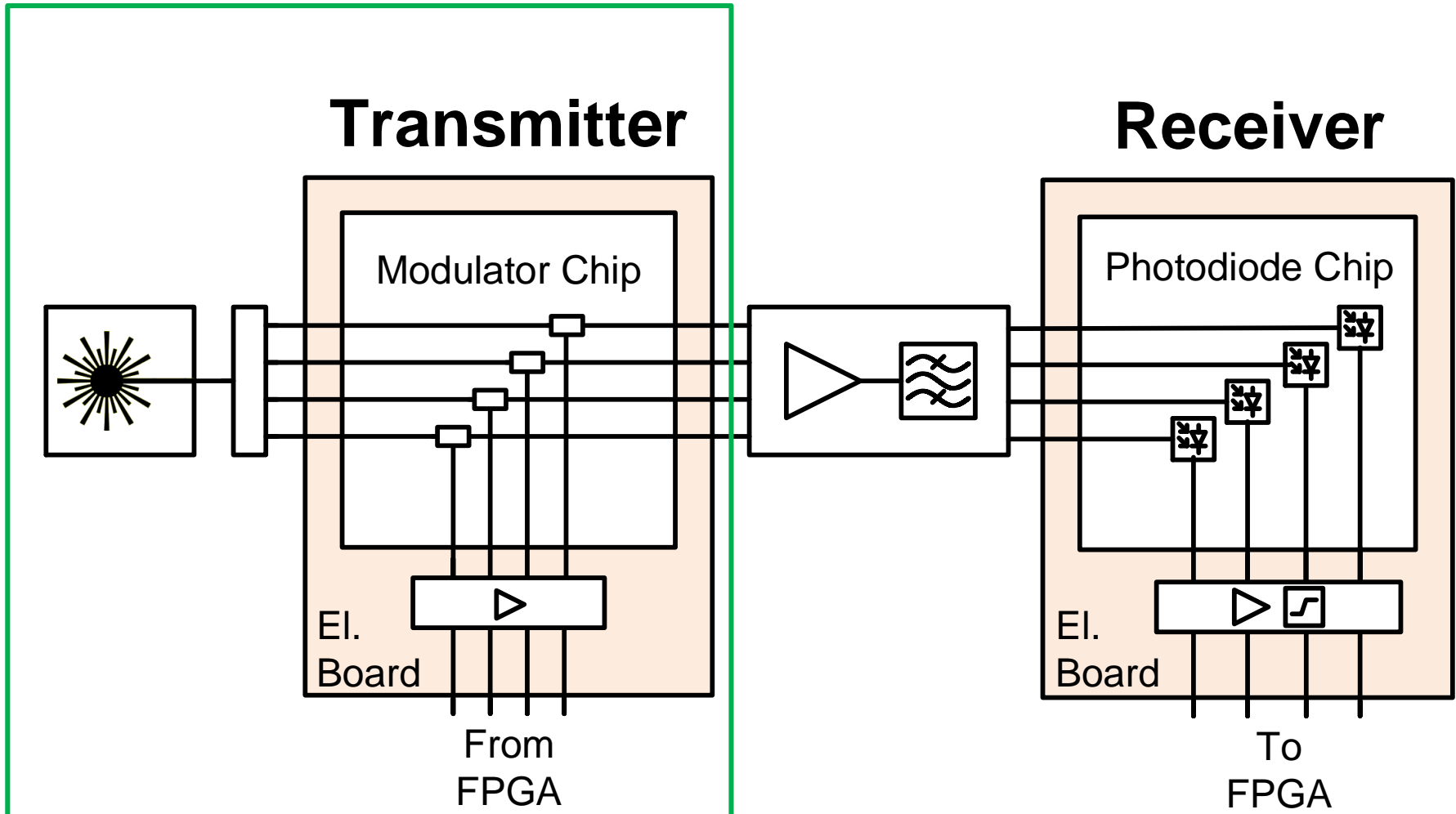
NAVOLCHI WP6

Integration, Characterization & Testing

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Demonstrator



Transmitter- PPM Chip (KIT)

Phase Modulator:

- Optical
 - Fed by external laser, split into four channels externally
 - Pitch between channels: 50 μm and 35 μm
 - Insertion loss (including GC): 30 dB
- Electrical
 - Pad pitch: 100 μm (85 μm x 85 μm , GSG)
 - Electrical probes or bonding for contacting
 - No 50 Ω termination on chip
- Electrooptic
 - $V_{\pi L}$: 1.1 Vmm (40 Gbit/s: 5 V_{pp}),
 - Bias or wavelength to determine operating point

Transmitter - FPGA

What ST does:

- Send the rtl for the FPGA
- Choose discrete components for implementing the analog parts
- Act as consultant for the partner(s) who will design and manufacture the board

What ETH does:

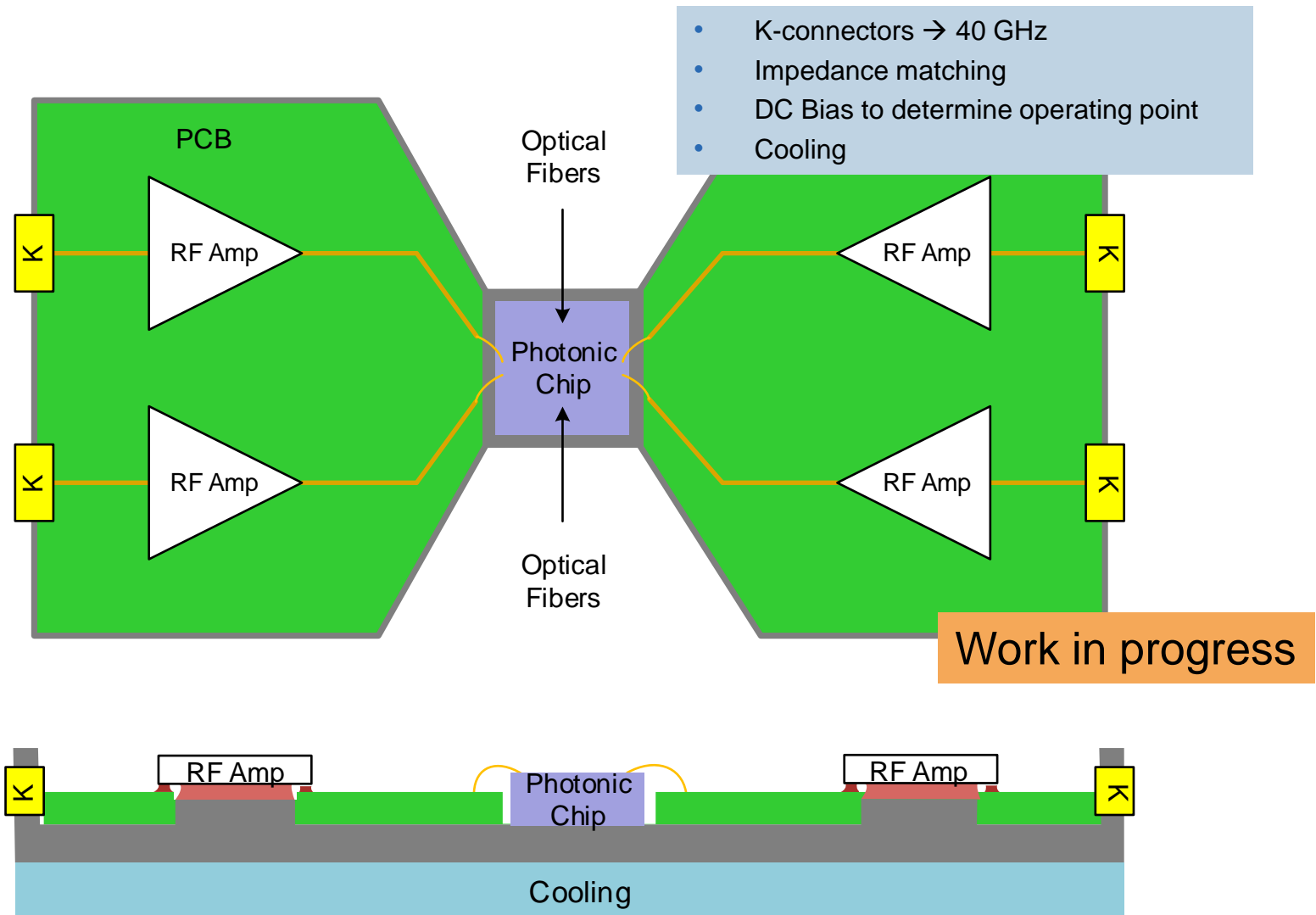
- Provide an FPGA (ST cannot move their FPGA somewhere else)
- Design and manufacture the electronic board (laser driver, modulator driver, etc.) with the discrete components
- Provide electrical wire bonding or pico-probes

Transmitter – Packaging

Main challenges

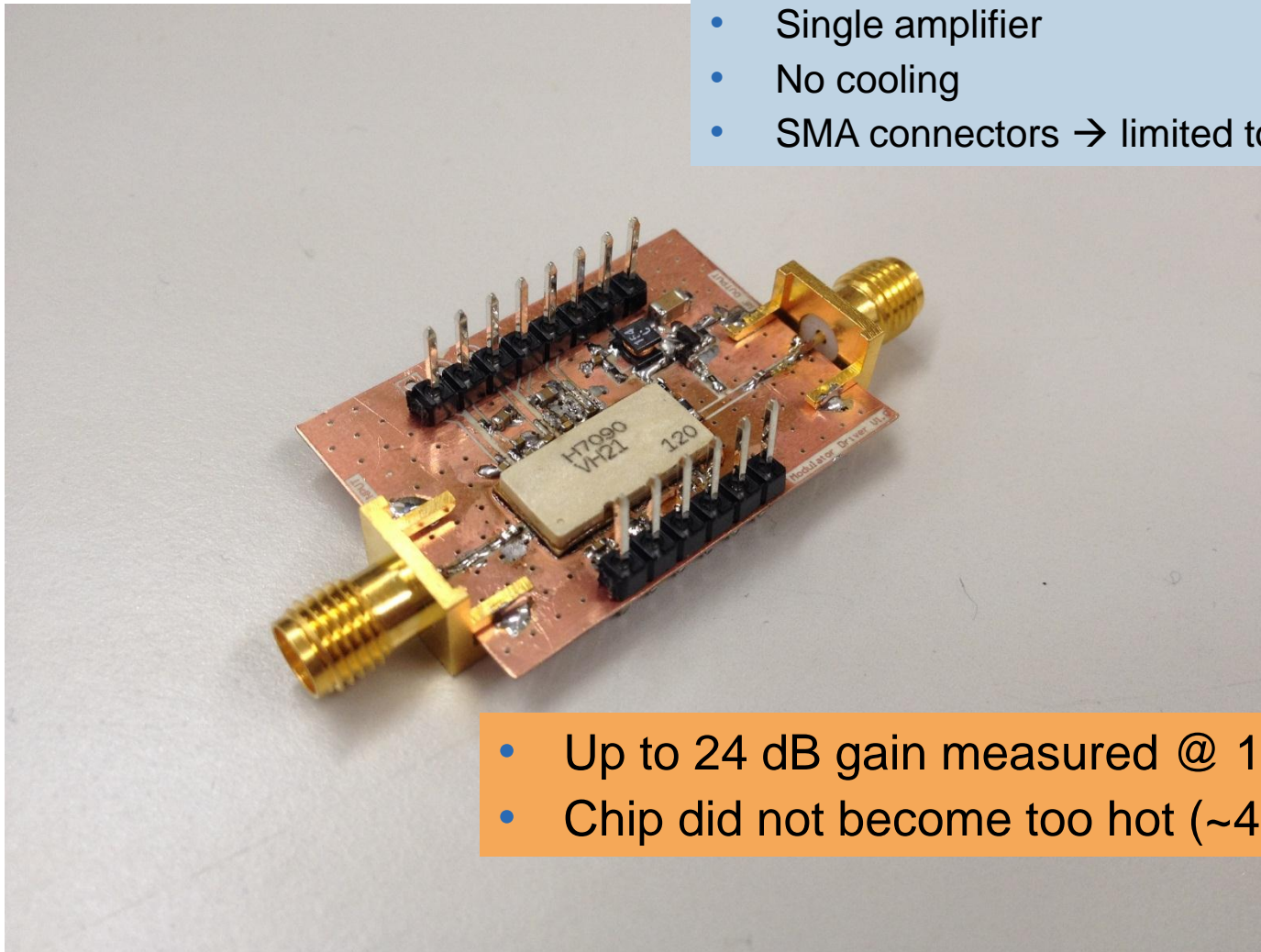
- Minimal light loss due to small pitch of 50 μm
- High frequencies require high precision alignment (K-connectors)
- High thermal density due to RF amplifiers

Transmitter –Electrical Board and Housing



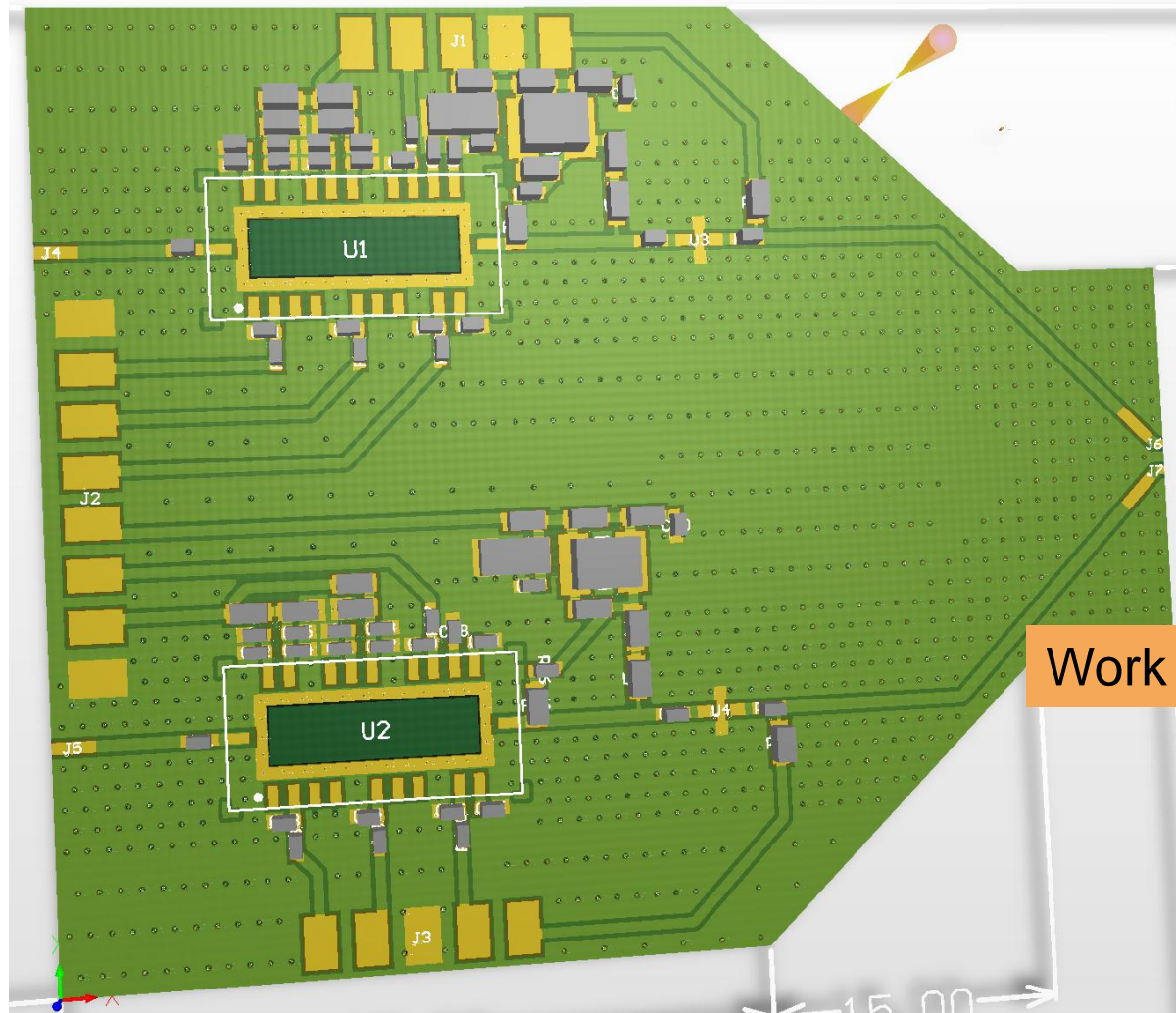
Transmitter – Prototype of Electrical Board

- Single amplifier
- No cooling
- SMA connectors → limited to 10 GHz



- Up to 24 dB gain measured @ 1 GHz
- Chip did not become too hot (~40 degC)

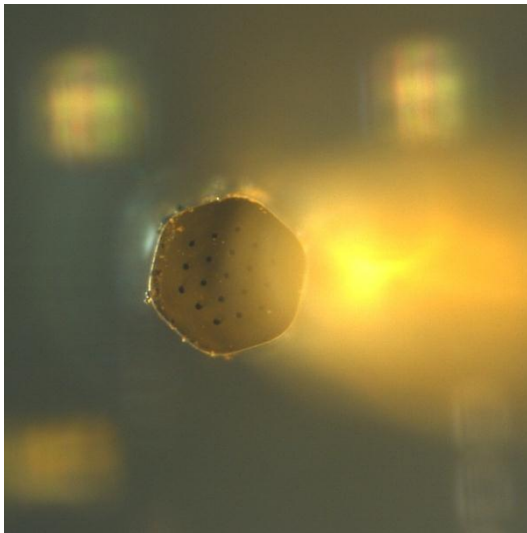
Transmitter – Final Electrical Board



Work in progress

Optical Link

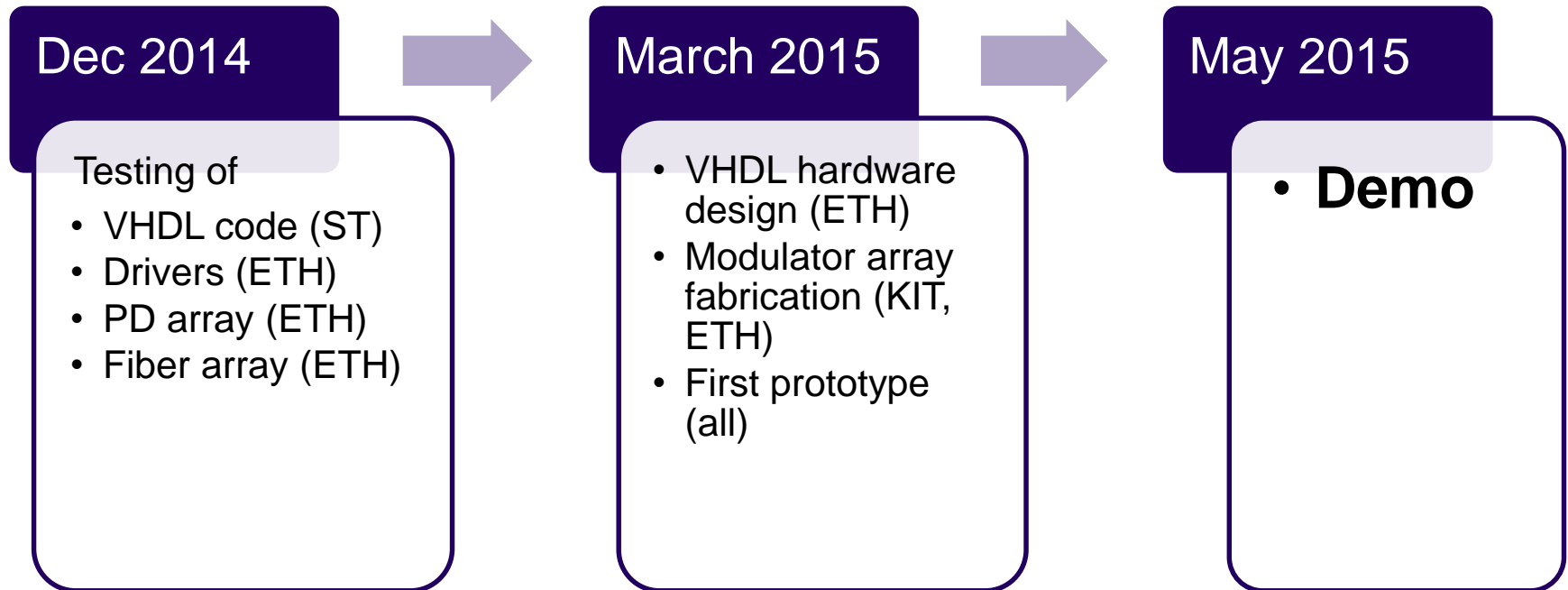
Multicore Fiber (Chiral Photonics)



Main challenge: fiber array alignment accuracy

- 19 channels with 50 μm pitch
- Interchannel coupling < -35 dB (datasheet)
- Allows for optical amplifier between transmitter and receiver

Timeline



VHDL code ST→ETH: 16.12.2014 ✓

Modulator drivers arrived at ETH: 08.12.2014 ✓

First prototype of board finished: 07.01.2015 ✓